

Plasma Etch System Competitive Specifications

Plasma Etch System: including-

- Durable Welded Rectangular Aluminum Vacuum Chamber; shall have approximate Inside dimensions equal to or bigger than 7.5"W x 8.5"D x 3.5"H for processing 6" diameter wafers
- Power Output: 400 Watt, 50 KHz Continuously Variable RF Power supply
- Vacuum-tight chamber with at least 5 CFM Direct Drive Oil Vacuum Pump, Oxygen Service (Krytox Charged).
- Gas flow control with at least 2 rotometers, 2 Gas Controls, 0-25 cc/min with precision needle valves.
- Vacuum gage: Thermocouple Vacuum Gauge, 0-1 Torr range, is acceptable
- Programmable Logic Controller (PLC) Microprocessor Control System shall have a Keypad user interface with alpha-numeric display and Storage of 1 process recipe for automatic process sequencing.
- System Console shall be no bigger than the dimensions; 20"W X 20"D X 24"H, due to the limited installation space allocation

Electrical: 120VAC, 15A.

Power Supply for High Frequency (HF) Configuration:

- Shall have 120W 13.56 MHz RF Power Supply with Automatic RF Matching Network. Continuously Variable with Digital Display (0-100W). In lieu of 50KHz power supply in item #1.